

L12	175	(US-20040159462-\$).did. or (US-3726002-\$ or US-3904934-\$ or US-4221047-\$ or US-4374868-\$ or US-4383363-\$ or US-4603023-\$ or US-4667220-\$ or US-4706167-\$ or US-4770900-\$ or US-4774126-\$ or US-4775573-\$ or US-4783722-\$ or US-4788766-\$ or US-4792646-\$ or US-4830264-\$ or US-4897918-\$ or US-4954877-\$ or US-4954878-\$ or US-4978639-\$ or US-5043794-\$ or US-5065227-\$ or US-5153987-\$ or US-5177594-\$ or US-5229647-\$ or US-5243142-\$ or US-5259110-\$).did. or (US-5263243-\$ or US-5319159-\$ or US-5346750-\$ or US-5384689-\$ or US-5404044-\$ or US-5438223-\$ or US-5440075-\$ or US-5470790-\$ or US-5473120-\$ or US-5474458-\$ or US-5478972-\$ or US-5481795-\$ or US-5484647-\$ or US-5493096-\$ or US-5515604-\$ or US-5536362-\$ or US-5576519-\$ or US-5599744-\$ or US-5608265-\$ or US-5619071-\$ or US-5638598-\$ or US-5652042-\$ or US-5674785-\$ or US-5675889-\$ or US-5689091-\$ or US-5699613-\$ or US-5717247-\$).did. or (US-5719354-\$ or US-5739585-\$ or US-5744862-\$ or US-5763939-\$ or US-5780143-\$ or US-5817405-\$ or US-5834848-\$ or US-5854507-\$ or US-5870289-\$ or US-5876842-\$ or US-5883335-\$ or US-5883426-\$ or US-5912510-\$ or US-5949030-\$ or US-5950306-\$ or US-5952611-\$ or US-6010769-\$ or US-6011311-\$ or US-6013948-\$ or US-6020629-\$ or US-6025648-\$ or US-6049129-\$ or US-6050832-\$ or US-6072233-\$ or US-6093969-\$ or US-6096411-\$ or US-6107109-\$).did. or (US-6110825-\$ or US-6114240-\$ or US-6119338-\$ or US-6130111-\$ or US-6137164-\$ or US-6169010-\$ or US-6177723-\$ or US-6188127-\$ or US-6198168-\$ or US-6201194-\$ or US-6203652-\$ or US-6204456-\$ or US-6211487-\$ or US-6222136-\$ or US-6235554-\$ or US-6239496-\$ or US-6243946-\$ or US-6270607-\$ or US-6271056-\$ or US-6274929-\$ or US-6281044-\$ or US-6281448-\$ or US-6294837-\$ or US-6297458-\$ or US-6297660-\$ or US-6303881-\$ or US-6307894-\$ or US-6319829-\$ or US-6325430-\$ or US-6329610-\$ or US-6335565-\$	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	ON	2005/05/18 08:44
Search History 5/18/05 12:56:20 PM Page 2 of 2 C:\Documents and Settings\US-6319829\Documents\US-6325430\Workspaces\%conductive-vias-laser-drill.wsp						

L13	7	"6620731"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 08:48
L14	3	"6833613"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 08:48
L15	50	"6294837"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 08:48
L16	114	"6107109"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 08:48
L17	130	13 14 15 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 08:49
L18	290	12 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 08:49
L19	231	18 and ((substrate board carrier) with (hole vias opening))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:02
L20	40	19 and ((solder near wave) capillary)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:18

L21	40	("5046239" "5063177" "5166097" "5172050" "5229647" "5236551" "5249450" "5420520" "5426072" "5483741" "5487999" "5495667" "5528080" "5541525" "5559444" "5578526" "5592736" "5607818" "5634267" "5674785" "5686317" "5716218" "5756395" "5781022" "5783461" "5796264" "5801452" "5815000" "5834945" "5869974" "5878485" "5896036" "5915977" "5929647" "5931685" "6107109" "6114240" "6242935" "6294837" "6314641").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 09:15
L22	45	("5046239" "5063177" "5172050" "5229647" "5236551" "5249450" "5404044" "5420520" "5426072" "5483741" "5487999" "5528080" "5541525" "5557844" "5578526" "5592736" "5607818" "5633122" "5634267" "5674785" "5686317" "5716218" "5781022" "5783461" "5783865" "5796590" "5801452" "5815000" "5834945" "5869974" "5876580" "5878485" "5896036" "5915977" "5929647" "5931685" "5936847" "5952840" "5962921" "6013948" "6040702" "6107109" "6107119" "6114240" "6162997").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 09:26
L23	89	("6107109").URPN.	USPAT	OR	ON	2005/05/18 09:31
L24	78	("4830264").URPN.	USPAT	OR	ON	2005/05/18 09:39
L25	5	("3871015" "4332341" "4412642" "4462534" "4708281").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 09:44

L26	57	("5046239" "5063177" "5172050" "5222014" "5229647" "5236551" "5249450" "5404044" "5420520" "5426072" "5483741" "5484647" "5487999" "5528080" "5541525" "5557844" "5578526" "5592736" "5607818" "5633122" "5634267" "5674785" "5686317" "5716218" "5739585" "5781022" "5783461" "5783865" "5796590" "5801452" "5815000" "5834945" "5869974" "5870289" "5876580" "5878485" "5896036" "5915977" "5929647" "5931685" "5936847" "5952840" "5962921" "6013948" "6040702" "6107109" "6107119" "6114240" "6162997" "6294837" "6353328" "6356098" "6362637" "6400172" "6417685" "6437591" "6451624").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/18 09:47
L27	248	18 and ((substrate board carrier) with ((hole vias opening) near4 (laser etching)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:03
L28	237	18 and ((substrate board carrier) with ((hole vias opening) near4 (laser (dry near etching))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:04
L29	40	20 and ((substrate board carrier) with ((hole vias opening) near4 (laser (dry near etching))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 11:52
L30	74	18 and ((substrate board carrier) with ((hole vias opening) near4 (laser (dry near etching))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:23

L31	23	30 and ((solder near wave) capillary)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:06
L32	51	30 not 31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:06
L33	3	18 and ((substrate board carrier) with ((hole vias opening) near4 (dry near etching)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:24
L34	216	((substrate board carrier) with (((through near hole) via) near4 (dry near1 etching)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:26
L35	59	34 and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:52
L36	59	35 not 31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 10:26
L37	28	19 and (solder near wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:23
L38	28	28 and (solder near wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:24

L39	0	38 not 37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:23
L40	0	34 and (solder near wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:24
L41	0	34 and (solder\$4 near wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:27
L42	669524	((through near hole) (conductive near via))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:26
L43	84896	42 with (substrate board carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:26
L44	1424	43 and (solder\$4 near wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:29
L45	109	44 and (solder near metal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:29